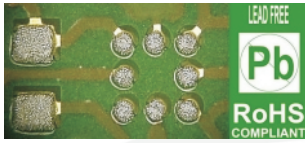


TECHNOLOGY / ALL PRODUCTS WITH LEAD OR **LEAD FREE (RoHS)**

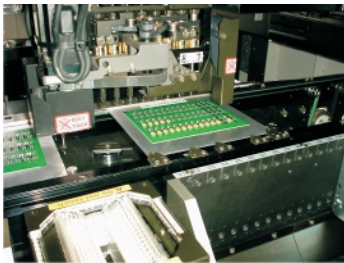
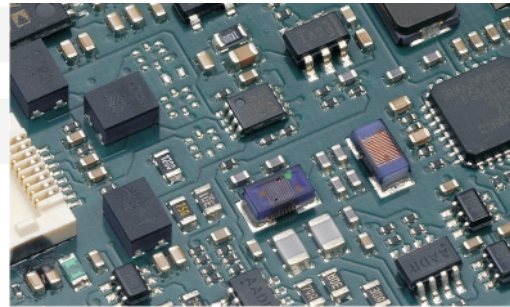


SOLDER PASTE APPLICATION

PRINTING WITH MASK OR SILK SCREEN
DISPENSING.

SUBSTRATES

THICK FILM CERAMIC
FR4, FR5, G10, G11, ROGERS
FLEX, RIGID FLEX, IMS
PYREX
...



COMPONENTS APPLICATION

UP TO 20'000 COMPONENTS/HOUR
POSITIONING ACCURACY: +/- 50µm

9 MILLION COMPONENTS IN 2008

HYBRID SA IS ABLE TO PERFORM SURFACE MOUNTED ELECTRONIC COMPONENTS ON SINGLE OR DOUBLE SIDED SUBSTRATES. REFERENCES FOR STANDARDS ARE:

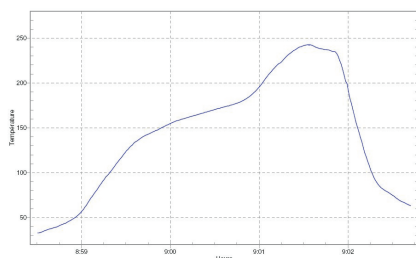
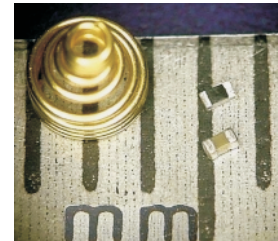
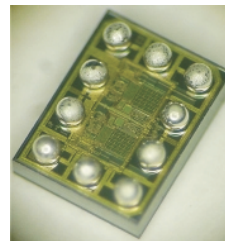
IPC/JEDEC J-STD-020D AND IPC-A-610 (REV.D) CLASS 3 IS APPLIED AS STANDARD.

COMPONENTS TYPES

STANDARD BOXES, FROM "0201"
STANDARD IC & PLCC, QFN, BGA, CSP,
FLIP-CHIP SOLDER BUMP.

EXOTIC COMPONENTS

TRANSFOS, COIL, CONICAL SPRINGS, QUARTZ,
CONTACTS BATTERY, ETC...



REFLOW

CONVECTION OVEN WITH CONVEYOR BELT

WASHING

FULLY AUTOMATIC WASHING SYSTEM
VAPOR PHASE RINING

